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For operation at lower loads and short circuit behavior see PMP5032 Test report

Modifications in Test:

R10 at 13.3k from COMP pin to ground gives most stable behavior at light loads.

Power and signal grounds on the HPA353 board that it was tested on were combined to a single ground plane to give best results in reducing duty cycle jitter and output ripple.

Snubber R6 + C12 changed from 0.68 ohms plus 2200pF to 0.47 ohms plus 3300pF; and R5 increased from 3.3 ohms to 4.7 ohms to reduce Vds overshoot on low side FET Q2 when Q1 turns on.

Thermal summary:

PMP5152: with snubber & gate drive updates to reduce max Vds on Q2 to 23V:

12.12Vin 3.98Ain 1.792Vout 24A 5.23W on board

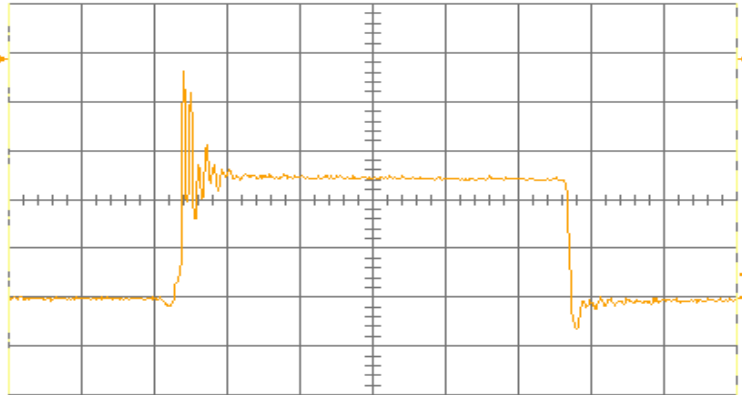
Hot spot R6 snubber 79.4 degrees; ambient 23-25 ; low side FET 73; hi side Q1 67.2; choke to 62.8, controller 47.6



Qq

Major waveform:

30-Sep-09
17:45:17



maximum(1) 23.13 V
 Freq(1) - - -
 pkpk(1) 26.41 V
 maximum(4) -10.9mV
 mean(4) -12.41mV

PMP5152 12.12Vin 3.98Ain 1.792Vout 24.0Aout
 TPS40303 controlled 2x CSD16312Q5 500LFM
 Snubber now 0.47 ohm plus 3300pF
 Boot R5 now 4.7 ohms
 Main waveform across Lo side FET Q2
 Close in ripple probe 10x 500MHz 9.5pF
 Max Vds = 23 V part rating 25V + avalanche

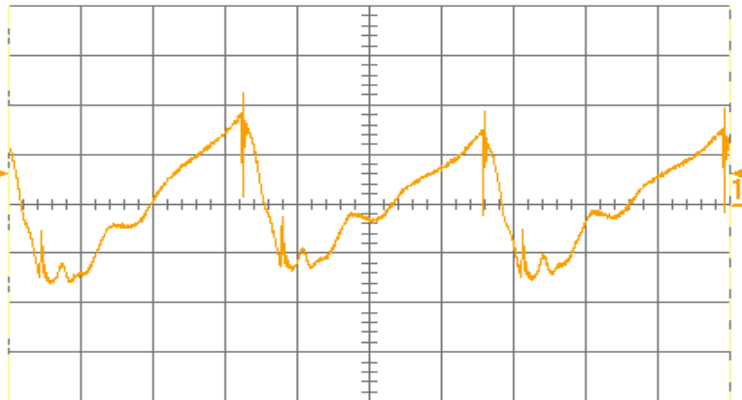
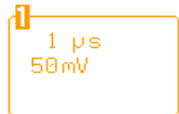
.1 μs
 1 .5 V DC 100
 2 1 V DC 100
 3 .5 V DC 100
 4 10 mV 500

1 DC 24.4 V

NORMAL

Input Ripple:

30-Sep-09
17:51:23



maximum(1) 114.0mV
 Freq(1) 1.44522 MHz
 pkpk(1) 193.8mV
 maximum(4) -9.9mV
 mean(4) -12.40mV

PMP5152 12.12Vin 3.98Ain 1.792Vout 24.0Aout
 TPS40303 controlled 2x CSD16312Q5 500LFM
 Snubber now 0.47 ohm plus 3300pF
 Boot R5 now 4.7 ohms
 Input ripple measured at 3 caps nearest input J1
 1x ripple probe but no 20MHz bandwidth
 about 160mV p-p ripple plus spikes
 12V bias on input caps reducing effective cap value

1 μs
 1 50 mV AC 100
 2 1 V DC 100
 3 .5 V DC 100
 4 10 mV 500

1 DC 34mV

STOPPED

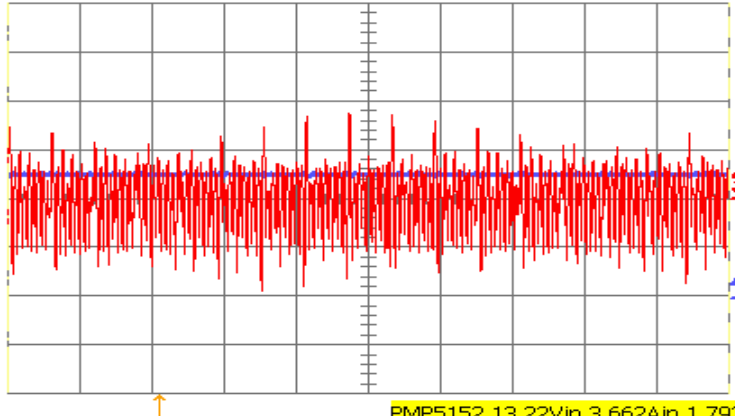
Qq

Output ripple:

6-Oct-09
17:47:09

50 μ s
10.0mV

50 μ s
10.0mV



PMP5152 13.22Vin 3.662Ain 1.793Vout 24.0Aout
TPS40303 controlled 2x CSD16312Q5 500LFM
Snubber now 0.47 ohm plus 3300pF
Boot R5 now 4.7 ohms
Signal ground & power ground tied together at bottom layer at several places and at C13 top layer
Output ripple measured at last output cap C28
1x ripple probe 20MHz bandwidth
37mV p-p

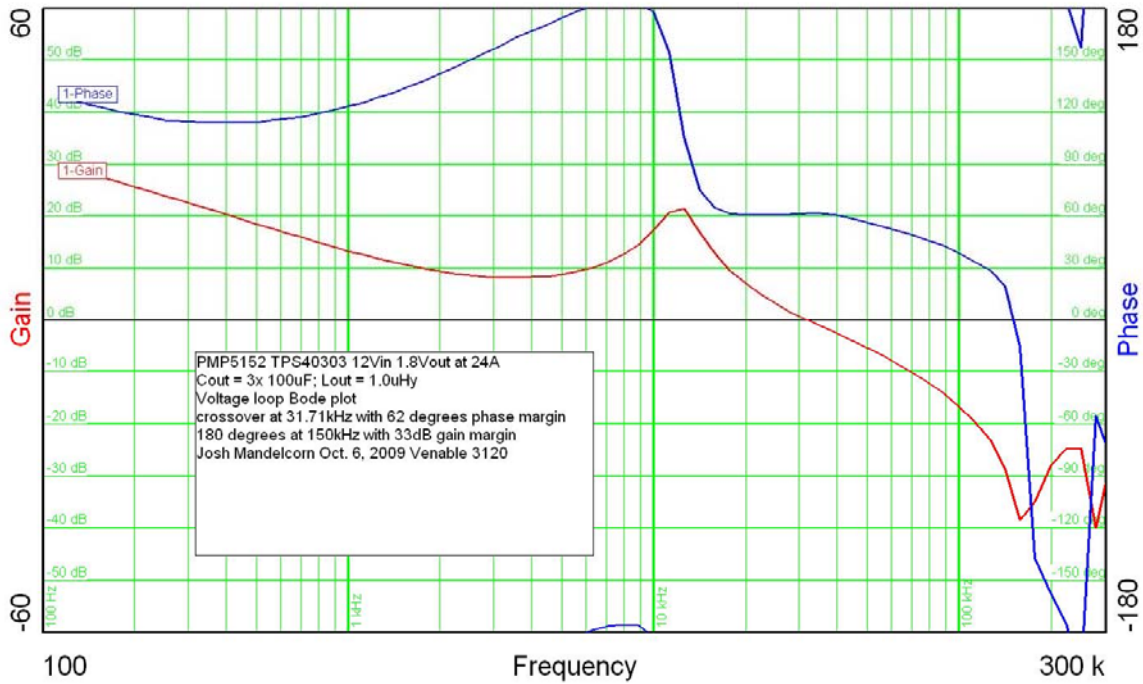
maximum(3) 17.5mV
Freq(3) 273.795 kHz
pkpk(3) 36.6mV
mean(3) 0.23mV
mean(4) 24.86mV

50 μ s BWL
1 .5 V DC
2 1 V DC
3 10 mV AC
4 10 mV 500

1 DC 8.7 V

STOPPED

Bode Plot:



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